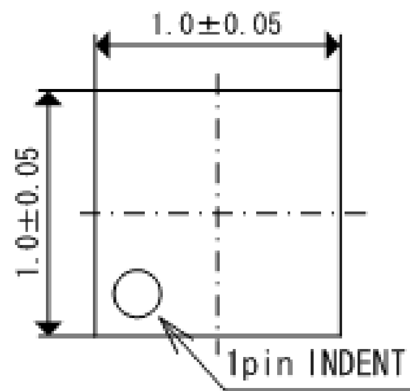
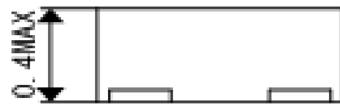
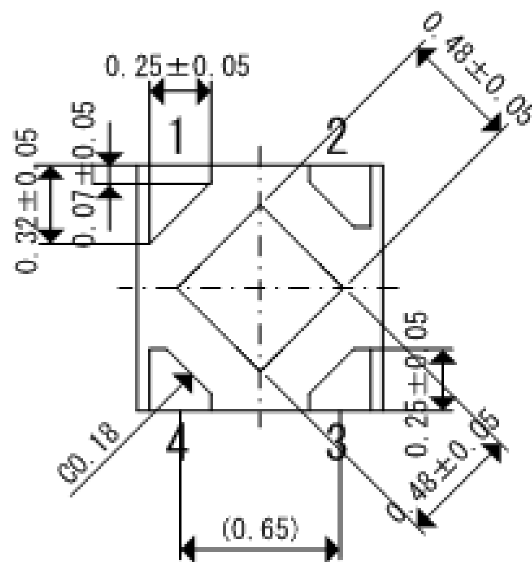
Package Information / Reference Pattern Layout Dimensions

●USPQ-4B03

Unit: mm

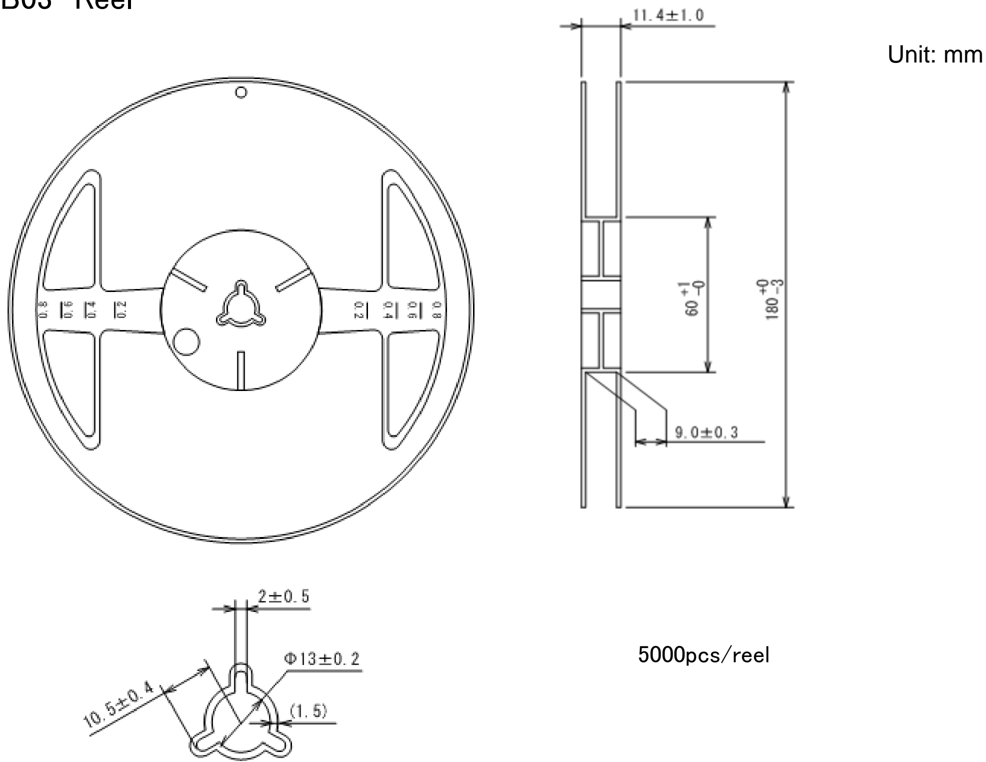




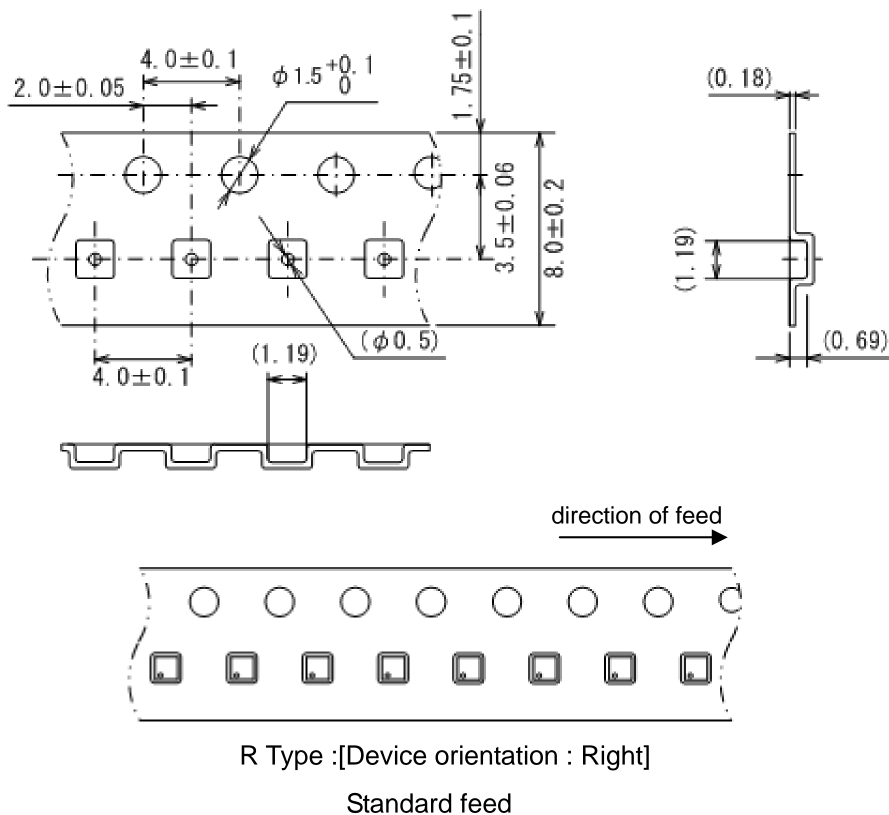


Taping Specifications

● USPQ-4B03 Reel



● Taping Specifications



R Type :[Device orientation : Right]

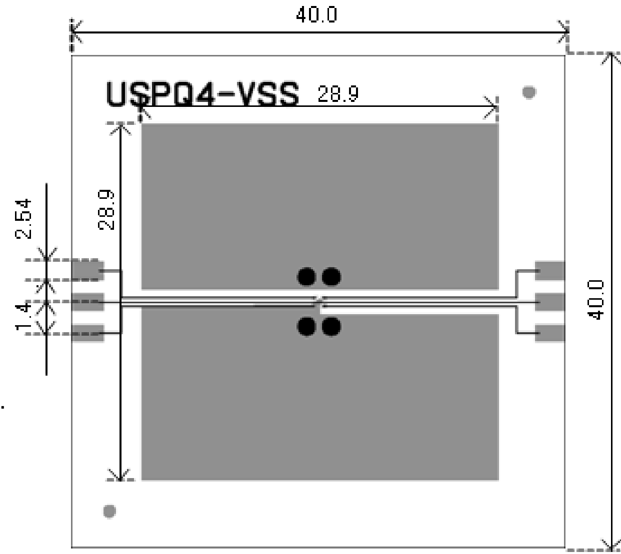
Standard feed

●USPQ-4B03 Power Dissipation

Power dissipation data for the USPQ-4B03 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition:	Mount on a board
Ambient:	Natural convection
Soldering:	Lead (Pb) free
Board Dimensions:	40 x 40 mm (1600mm2)
Board Structure:	4 Copper Layers
	Each layer is connected to the package heat-sink and terminal pin No.1.
	Each layer has approximately 800mm2 copper area.
Material:	Glass Epoxy (FR-4)
Thickness:	1.6 mm
Through-hole:	4 x 0.8 Diameter

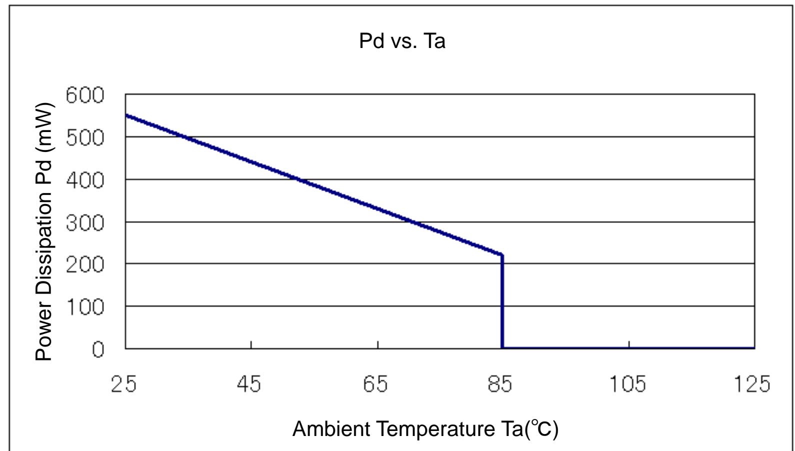


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature (85℃)

Board Mount (Tjmax=125℃)

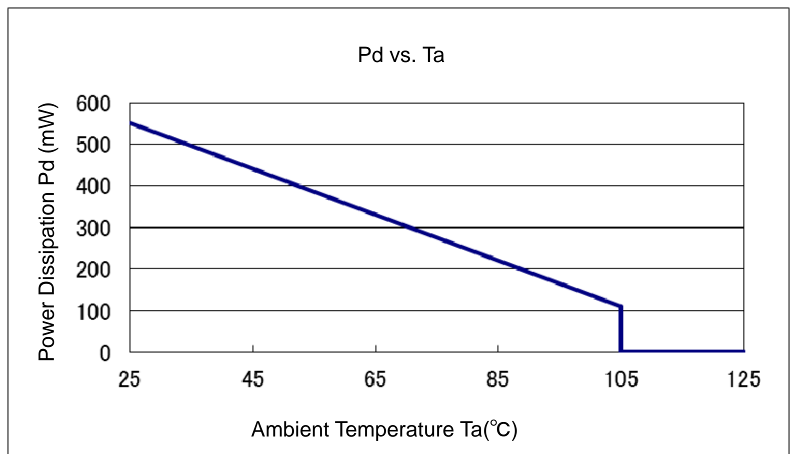
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	550	181.82
85	220	



3. Power Dissipation vs. Ambient Temperature (105℃)

Board Mount (Tjmax=125℃)

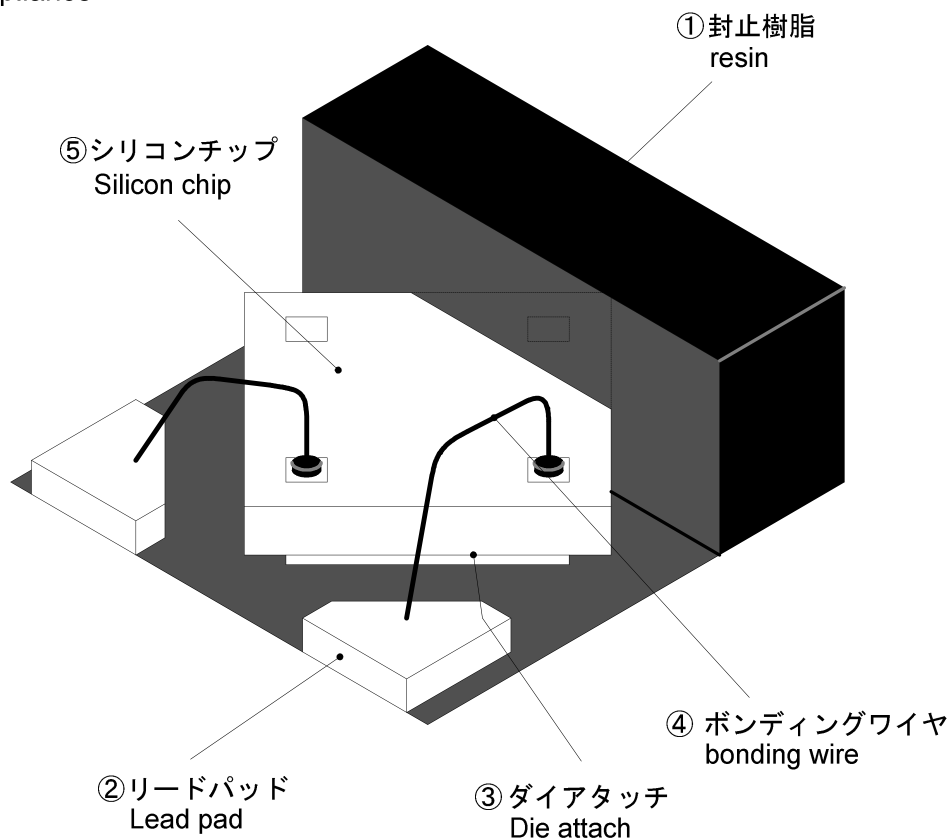
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	550	181.82
85	110	



TOIREX

USPQ-4B03構造図
USPQ-4B03 Perspective

RoHS対応品
RoHS Compliance



項 目 item		材 料 material	備 考 Note
①	封止樹脂 resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードパッド Lead pad	ニッケル Nickel	
	端子処理 outer pad plating	Auメッキ Gold plating	端子側面は除く Except the side of the terminals.
③	ダイアタッチ Die attach	エポキシ Epoxy	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Silicon chip	Si	

捺印表示 marking	レーザー laser marking